



Per OSHPark specs,  
min trace 5mil,  
min space 5mil's,  
min ringlet 4 mil's.  
4 layer board stackup is as follows:  
T-0 is top min 1 oz copper (1.4 mil)  
min 6.7 mil prepreg FR4  
T-1 is GND min 0.5 oz copper (0.7 mil)  
min 47 mil core FR4  
T-2 is PWR min 0.5 oz copper (0.7 mil)  
min 6.7 mil prepreg FR4  
T-3 is bottom min 1 oz copper (1.4 mil)

<http://rusefi.com/>

Sheet:

File: O2\_input\_CJ125.kicad\_pcb

Title: CJ125 Wide O2

Size: A Date: 2018-06-17

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